

## Features

- Fast switching
- Low Gate Charge
- Improved dv/dt capability
- 100% avalanche tested
- Green Device Available

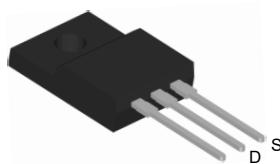
## Product Summary



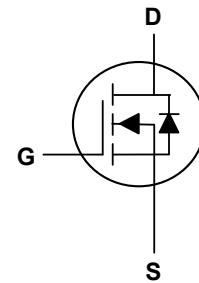
$V_{DS}$	650	V
$I_D$	16	A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	0.49	$\Omega$

## Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- AC to DC Converters



TO-220F Top View



## Absolute Maximum Ratings( $T_c=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Continuous Drain Current <sup>1</sup>	$I_D @ T_c = 25^\circ\text{C}$	16	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	64	A
Single Pulse Avalanche Energy <sup>3</sup>	EAS	1800	mJ
Total Power Dissipation <sup>4</sup>	$P_D$	65	W
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ\text{C}$
Operating Junction Temperature Range	$T_J$	-55 to 150	$^\circ\text{C}$

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	100	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-Case	$R_{\theta JC}$	1.79	$^\circ\text{C}/\text{W}$

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	650	---	---	V
Static Drain-Source On-Resistance <sup>2</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}$ , $I_D=8\text{A}$	---	0.46	0.49	$\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	2	---	3.5	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=650\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 30\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$
Total Gate Charge	$Q_g$	$V_{\text{DD}}=325\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=16\text{A}$	---	60	---	nC
Gate-Source Charge	$Q_{\text{gs}}$		---	11	---	
Gate-Drain Charge	$Q_{\text{gd}}$		---	24	---	
Turn-On Delay Time	$T_{\text{d(on)}}$	$V_{\text{DD}}=325\text{V}$ , $R_G=9.1\Omega$ , $I_D=16\text{A}$	---	33	---	ns
Rise Time	$T_r$		---	78	---	
Turn-Off Delay Time	$T_{\text{d(off)}}$		---	170	---	
Fall Time	$T_f$		---	80	---	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	2400	---	pF
Output Capacitance	$C_{\text{oss}}$		---	22.3	---	
Reverse Transfer Capacitance	$C_{\text{rss}}$		---	105	---	

**Drain-Source Diode Characteristics**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current <sup>1</sup>	$I_s$	$T_c=25^\circ\text{C}$	---	---	16	A
Pulsed Source Current <sup>2</sup>	$I_{\text{SM}}$		---	---	64	A
Diode Forward Voltage <sup>2</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}$ , $I_s=16\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.5	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F=16\text{A}$ , $dI_F/dt=100\text{A}/\mu\text{s}$	---	350	---	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		---	3.3	---	$\mu\text{C}$

**Note:**

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature

## Typical Characteristics

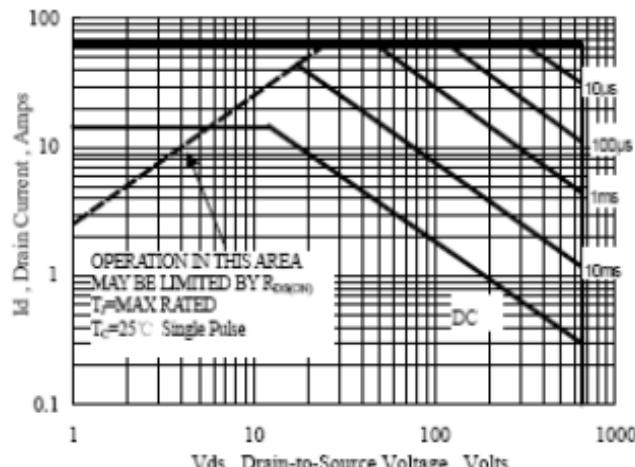


Figure 1 Maximum Forward Bias Safe Operating Area

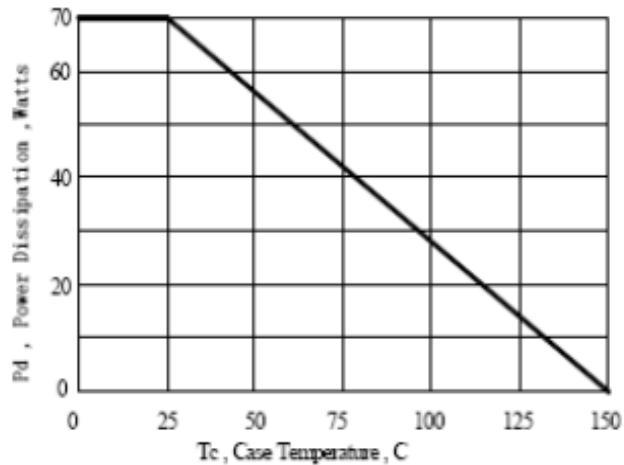


Figure 2 Maximum Power Dissipation vs Case Temperature

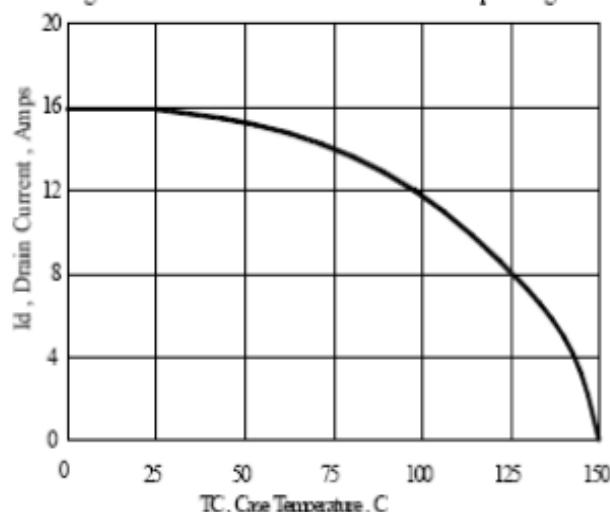


Figure 3 Maximum Continuous Drain Current vs Case Temperature

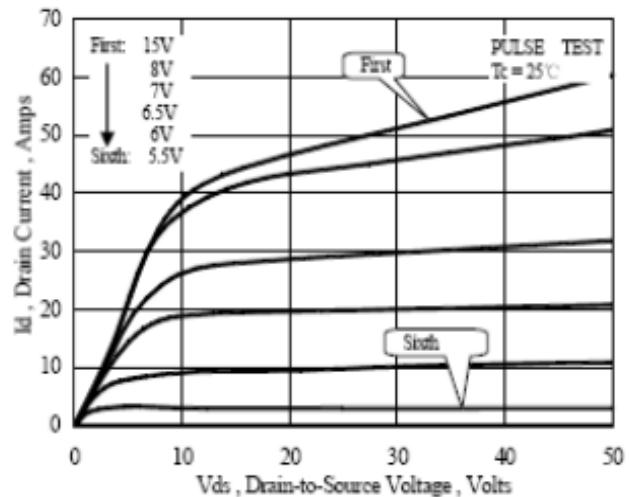


Figure 4 Typical Output Characteristics

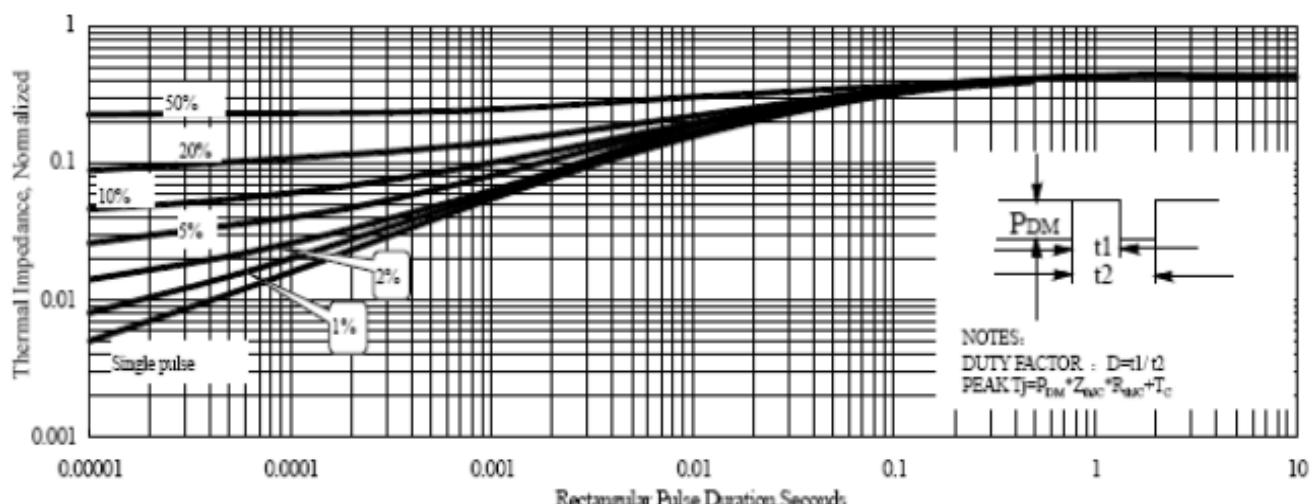


Figure 5 Maximum Effective Thermal Impedance, Junction to Case

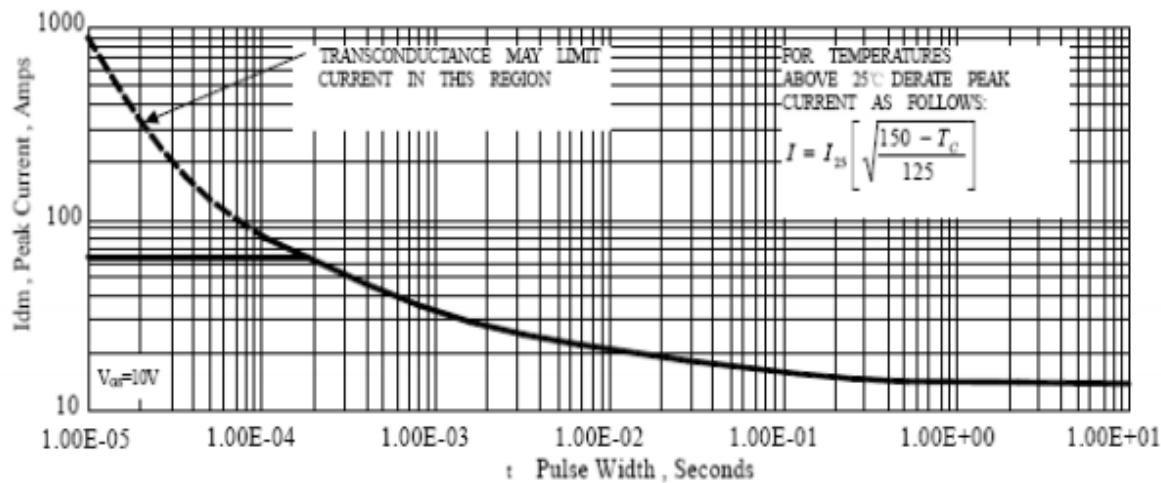


Figure 6 Maximum Peak Current Capability

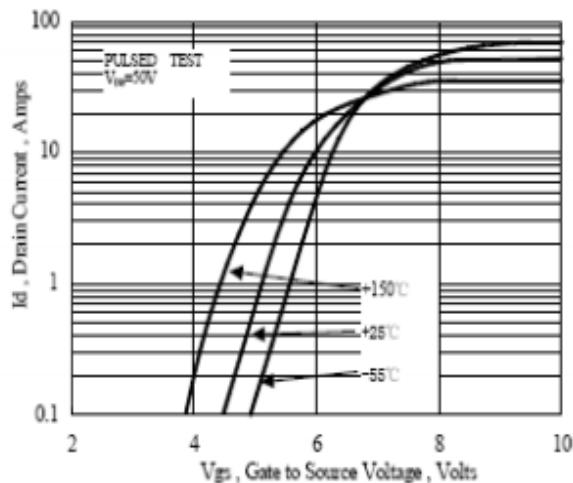


Figure 7 Typical Transfer Characteristics

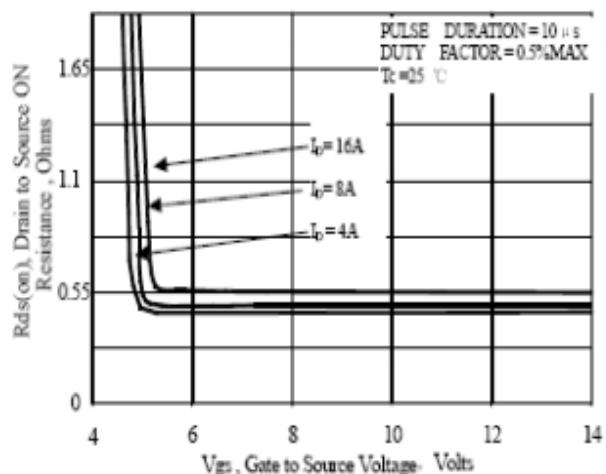


Figure 8 Typical Drain to Source ON Resistance vs Gate Voltage and Drain Current

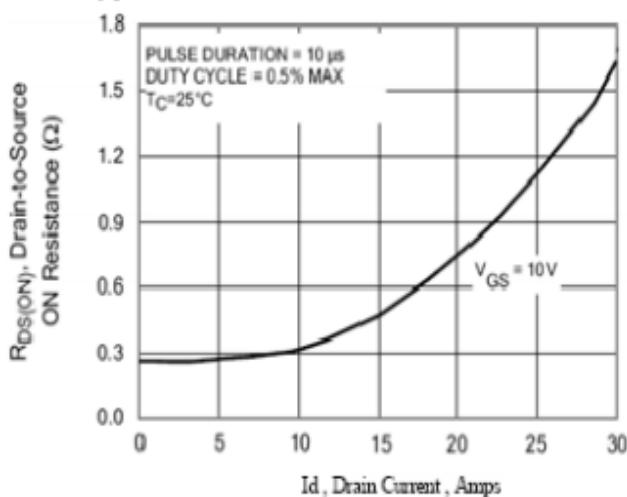


Figure 9 Typical Drain to Source ON Resistance vs Drain Current

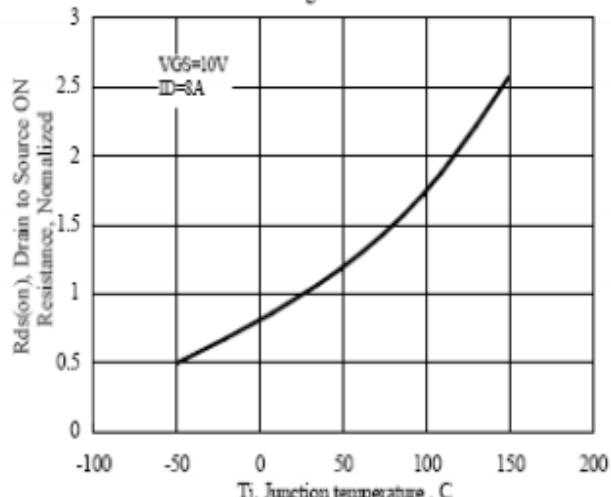
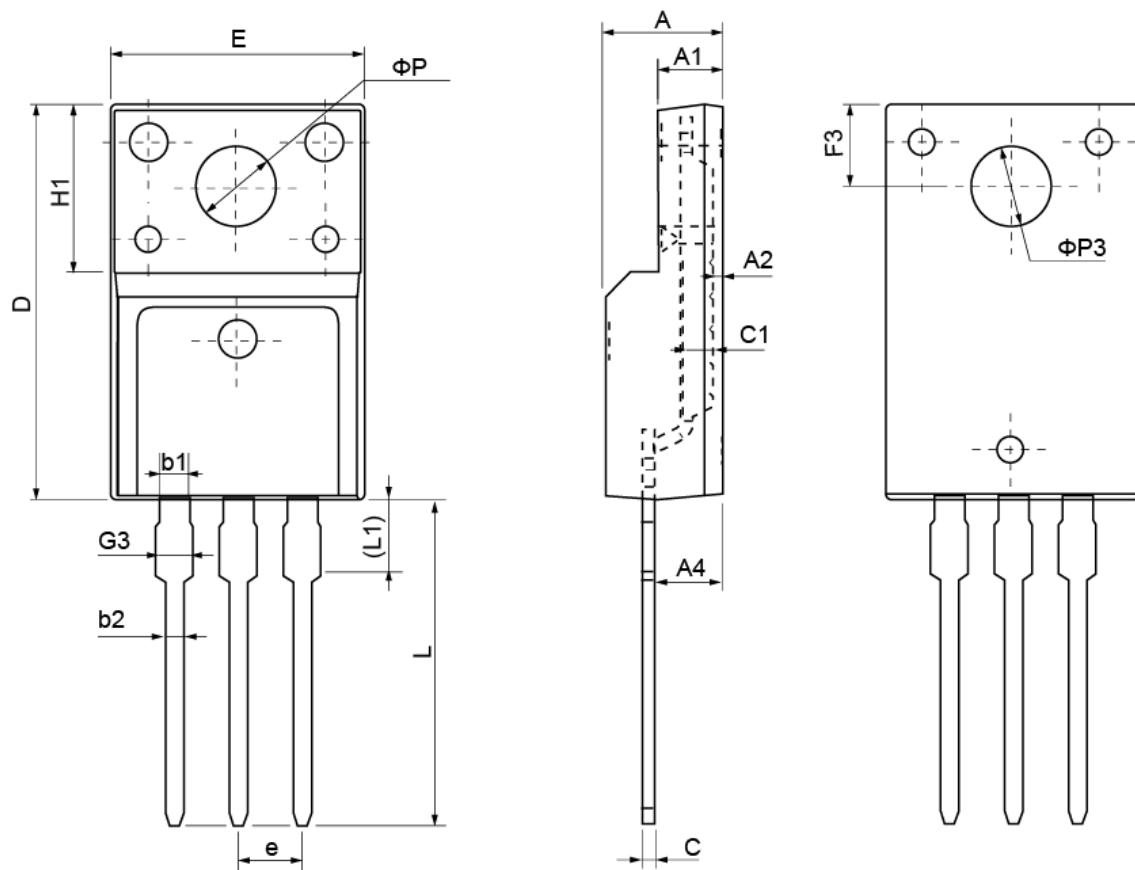


Figure 10 Typical Drain to Source on Resistance vs Junction Temperature

### TO-220F Package Outline Dimensions



<b>Symbol</b>	<b>Dimensions (unit:mm)</b>			<b>Symbol</b>	<b>Dimensions (unit:mm)</b>		
	<b>Min</b>	<b>Typ</b>	<b>Max</b>		<b>Min</b>	<b>Typ</b>	<b>Max</b>
<b>A</b>	4.40	4.70	5.00	<b>H1</b>	6.70 REF		
<b>A1</b>	2.30	2.55	2.80	<b>L</b>	12.30	12.98	13.30
<b>A2</b>	0.30	0.50	0.70	<b>L1</b>	2.95	3.10	3.50
<b>A4</b>	2.45	2.80	3.05	<b>φ P</b>	3.03	3.20	3.50
<b>c</b>	0.30	0.50	0.70	<b>φ P3</b>	3.15	3.45	3.65
<b>c1</b>	1.20	1.30	1.40	<b>b1</b>	1.10	1.30	1.45
<b>D</b>	15.40	15.90	16.40	<b>b2</b>	0.60	0.80	1.00
<b>E</b>	9.86	10.16	10.46	<b>F3</b>	3.05	3.30	3.55
<b>e</b>	2.54 BSC			<b>G3</b>	1.15	1.35	1.55